

# Electronic radiation hardening – Radiation Hardness Assurance and Technology Demonstration Activities

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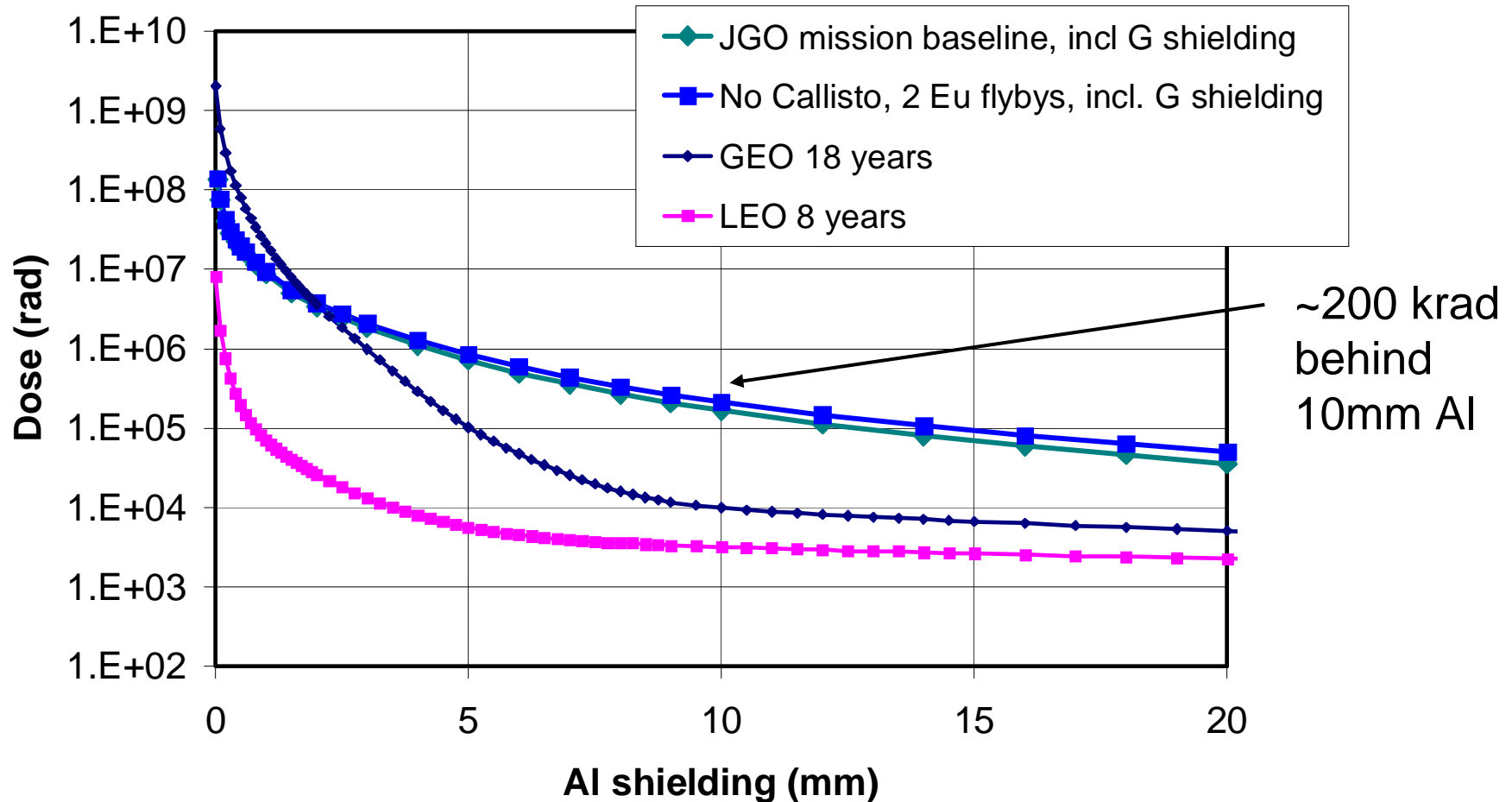
# Radiation Effects in electronics

- Radiation environment is a significant constraint for any space missions
- The Jupiter environment is very demanding
  - The electron environment is particularly harsh
  - Proton and heavy ion environments similar to other interplanetary missions
- Radiation hardness assurance of electronic components and systems for Laplace instruments will require interactions between teams
  - Environment specialists
  - Radiation effects engineers
  - System designers

# Outline

- Laplace radiation environment at the component level
  - Radiation hardness assurance
    - TID
    - TNID
    - SEE
- } Radiation Design Margin (RDM)
- Technology Demonstration Activities
    - Critical components for power systems
    - Optocouplers, sensors and detectors
    - Radiation testing of candidate memory devices for Laplace mission
    - Characterisation of front end and mixed signal ASICs (to be initiated)

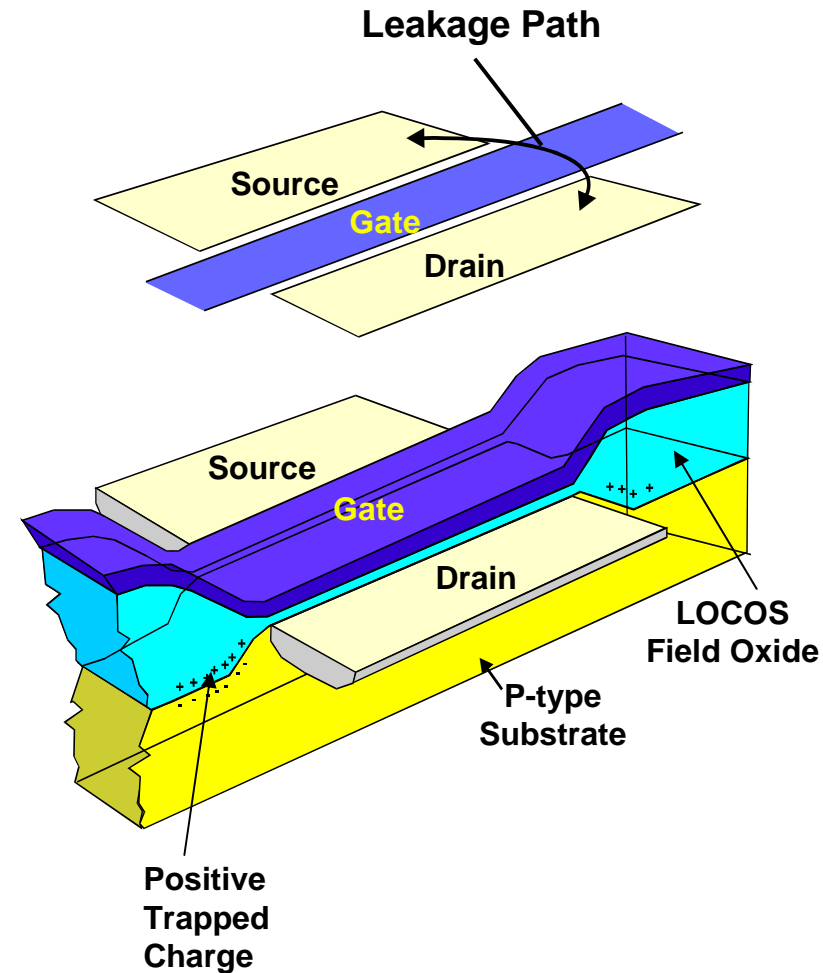
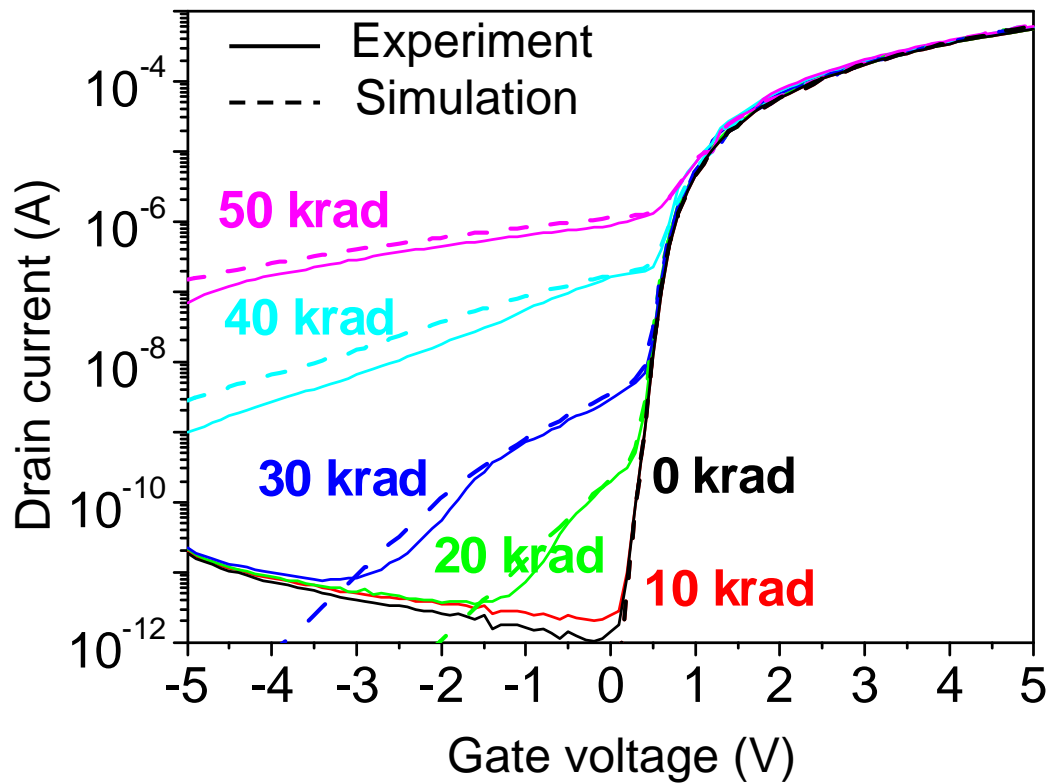
# Laplace Radiation Environment - TID



After [Ch. Erd, "Laplace environment specification, 14 June 2011"]

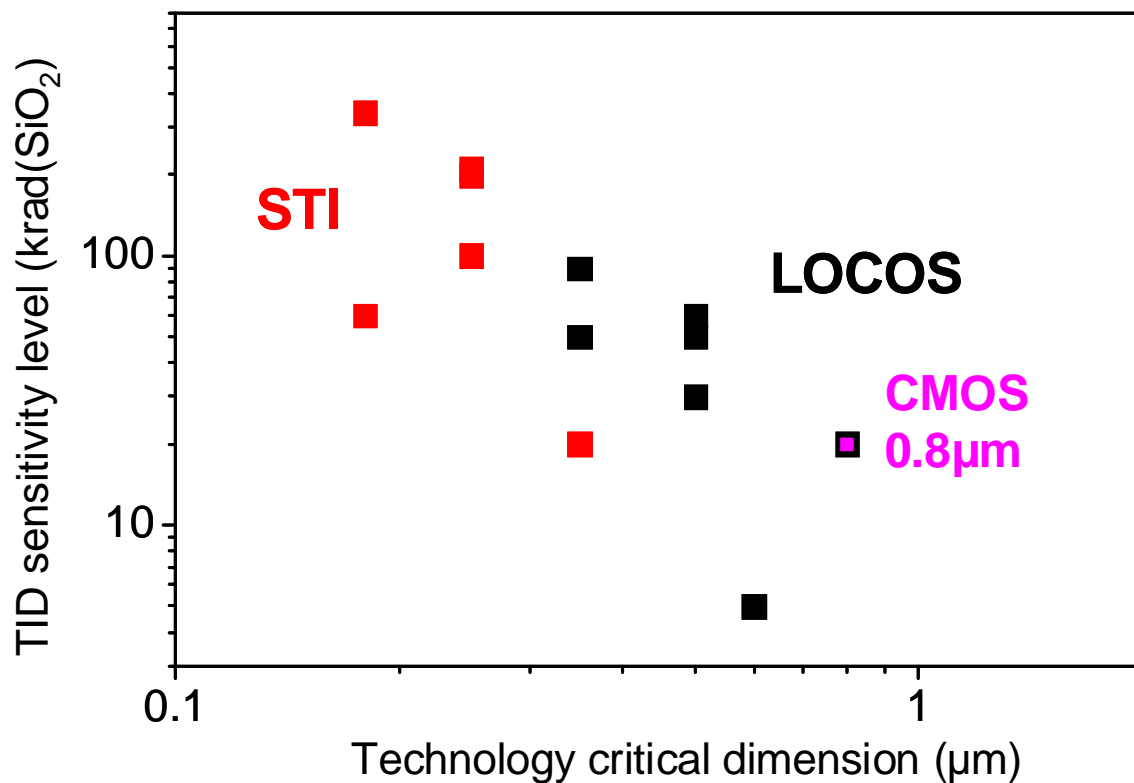
# Typical TID effect in CMOS: charge buildup in gate and field oxides induces leakage currents

CMOS technology 0.8 $\mu$ m,  
LOCOS isolation



[Ferlet HDR05]

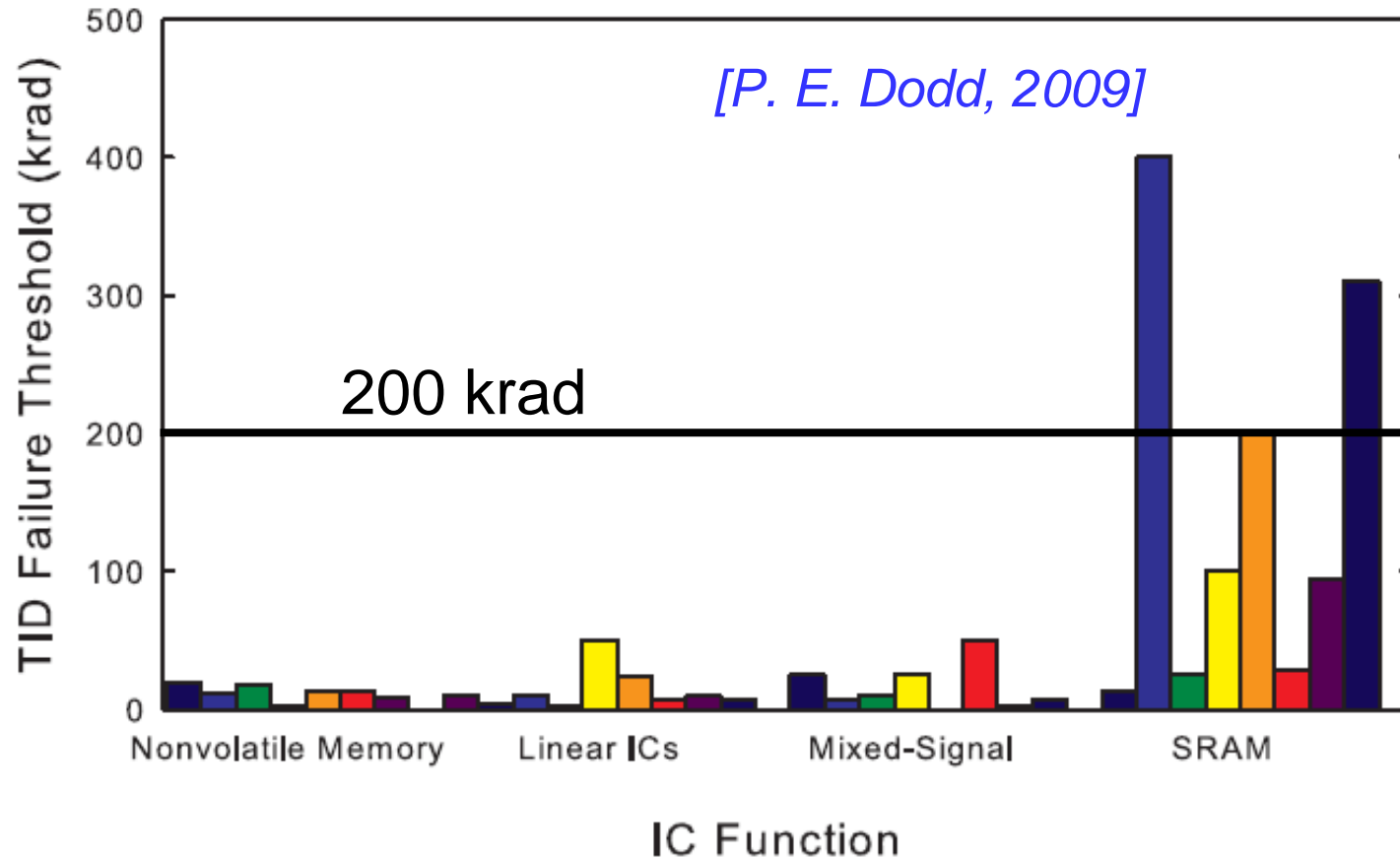
# Highly scaled CMOS technologies, with standard design, are less sensitive to TID



Design with rad-hard libraries, like DARE, improves TID hardness, compared to standard designs

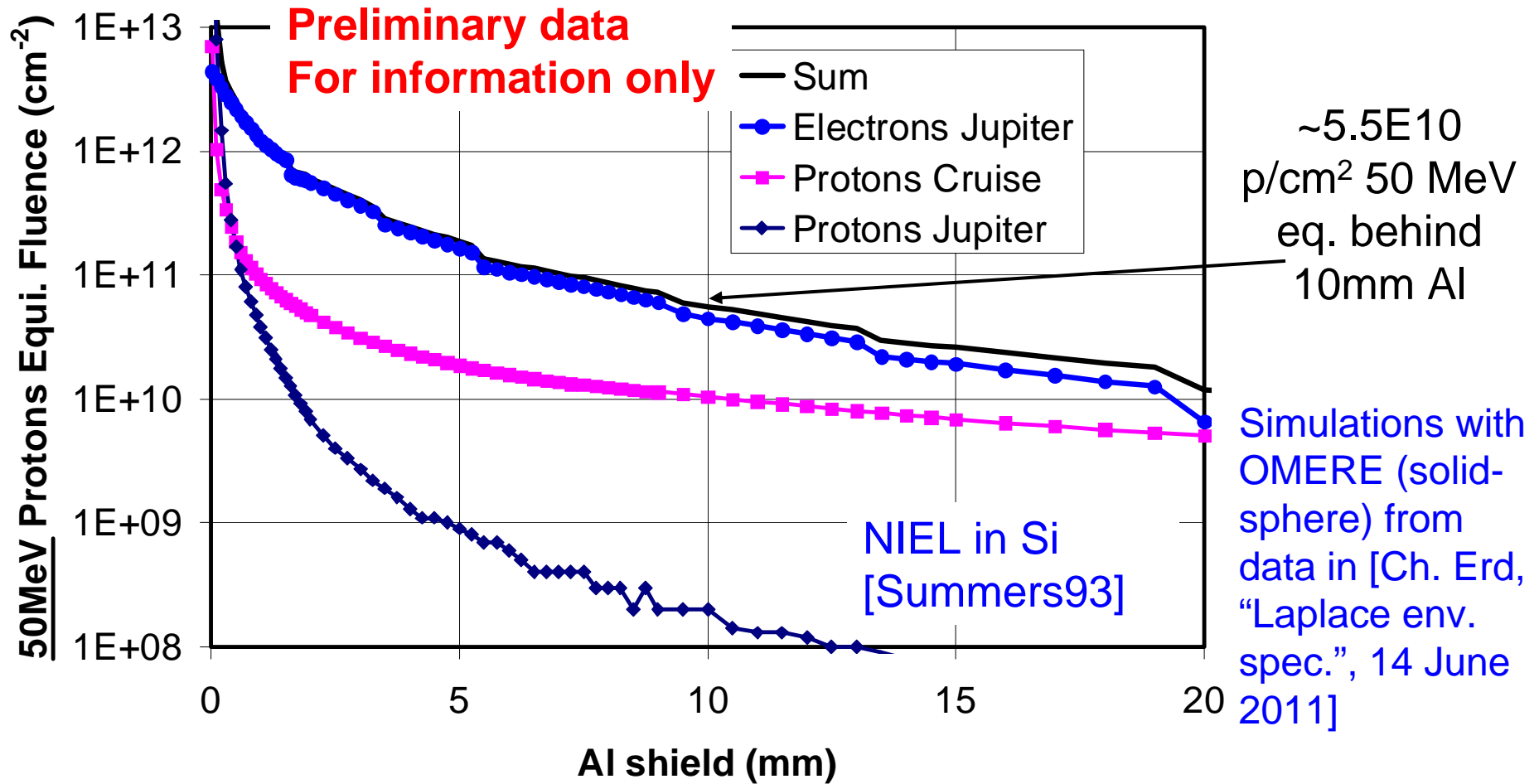
Compilation from [Lacoe03, Anel97, Kerwin98, Shaneyfelt98, Brady99, Lacoe99, Lacoe00, Lacoe01, Nowlin04]

However, real systems use a wide variety of IC technology generations, for which TID hardening is not granted



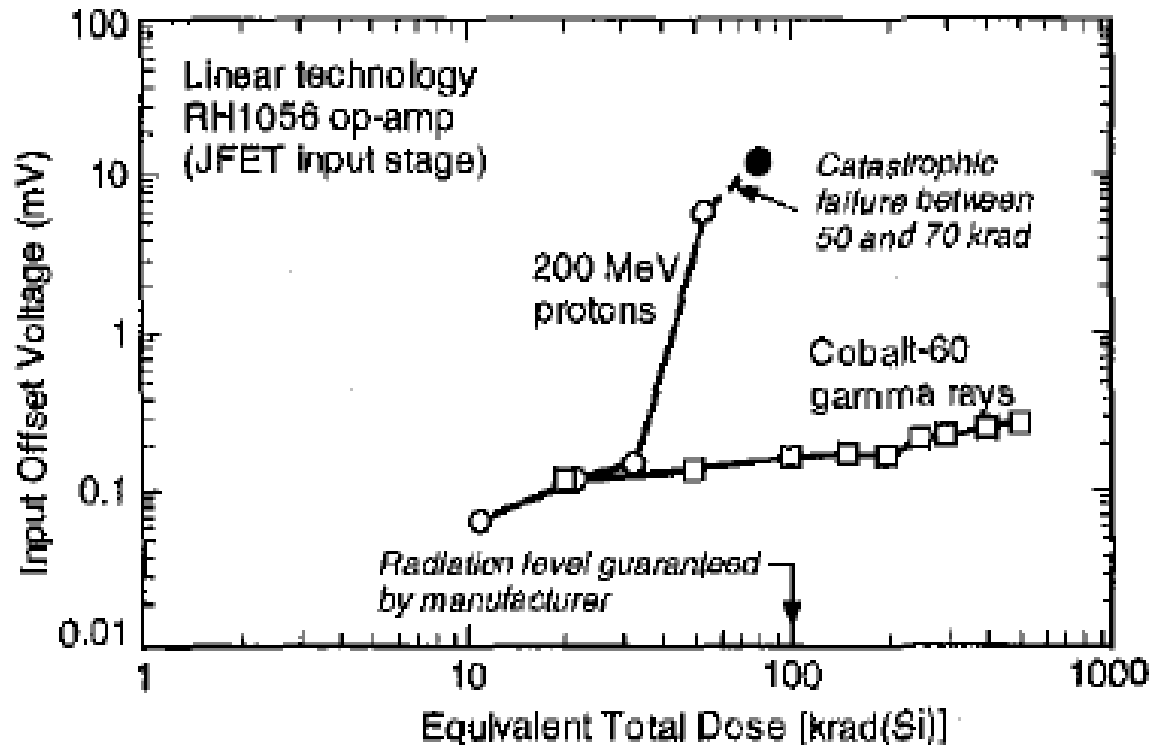
Compilation from Radiation Effect data workshops between 2002 and 2004

# Laplace Radiation Environment - TNID





Because of displacement damage,  
some circuits fail at much lower equivalent total  
dose levels compared to gamma rays



50-70 krad  
corresponds to  
**2E10 cm<sup>-2</sup>**  
**50MeV protons**

[B. G. Rax et al.  
TNS Dec. 1999]

Figure 1. Degradation of the RH1056 op-amp from protons and gamma rays.

# The SEE requirements for Laplace are similar to other space missions

SEE LET Threshold	Analysis Requirement
$> 60 \text{ MeVcm}^2/\text{mg}$	SEE risk negligible, no further analysis needed
$15 \text{ MeVcm}^2/\text{mg} < \text{LET}_{\text{threshold}} < 60 \text{ MeVcm}^2/\text{mg}$	SEE risk, heavy ion induced SEE rates to be analyzed
$\text{LET}_{\text{threshold}} < 15 \text{ MeVcm}^2/\text{mg}$	SEE risk high, heavy ion and proton induced SEE rates to be analyzed

[ECSS-Q-ST-60-15C, draft]

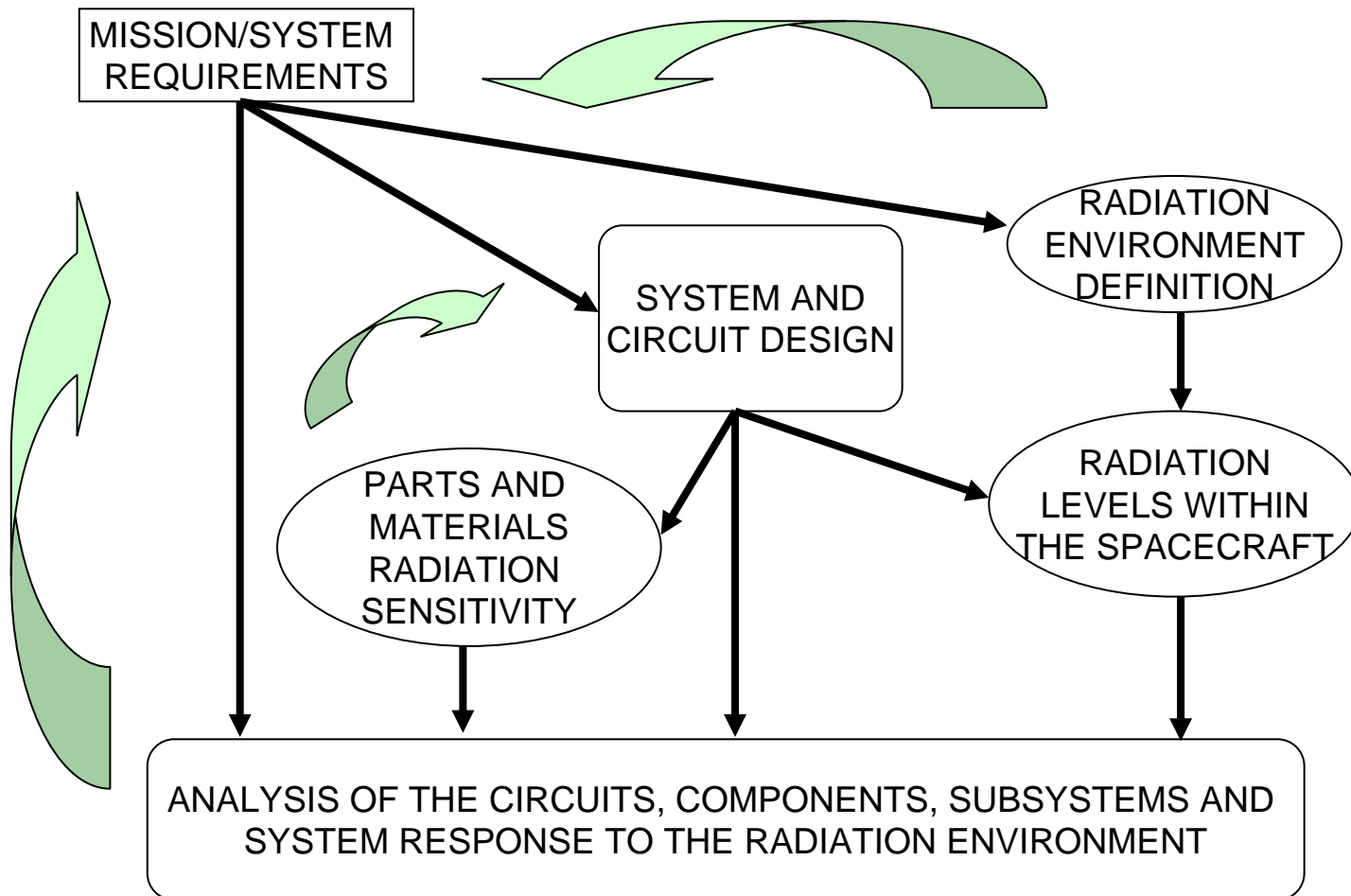
# What is Radiation Hardness Assurance (RHA) ?

- RHA consists of all activities undertaken to ensure that the electronics and materials of a space system perform to their design specifications after exposure to the space radiation environment
- Deals with environment definition, part selection, part testing, spacecraft layout, radiation tolerant design, mission/system/subsystems requirements, mitigation techniques, etc.
- Radiation Hardness Assurance goes beyond the piece part level

# RHA Requirements and TID test standard

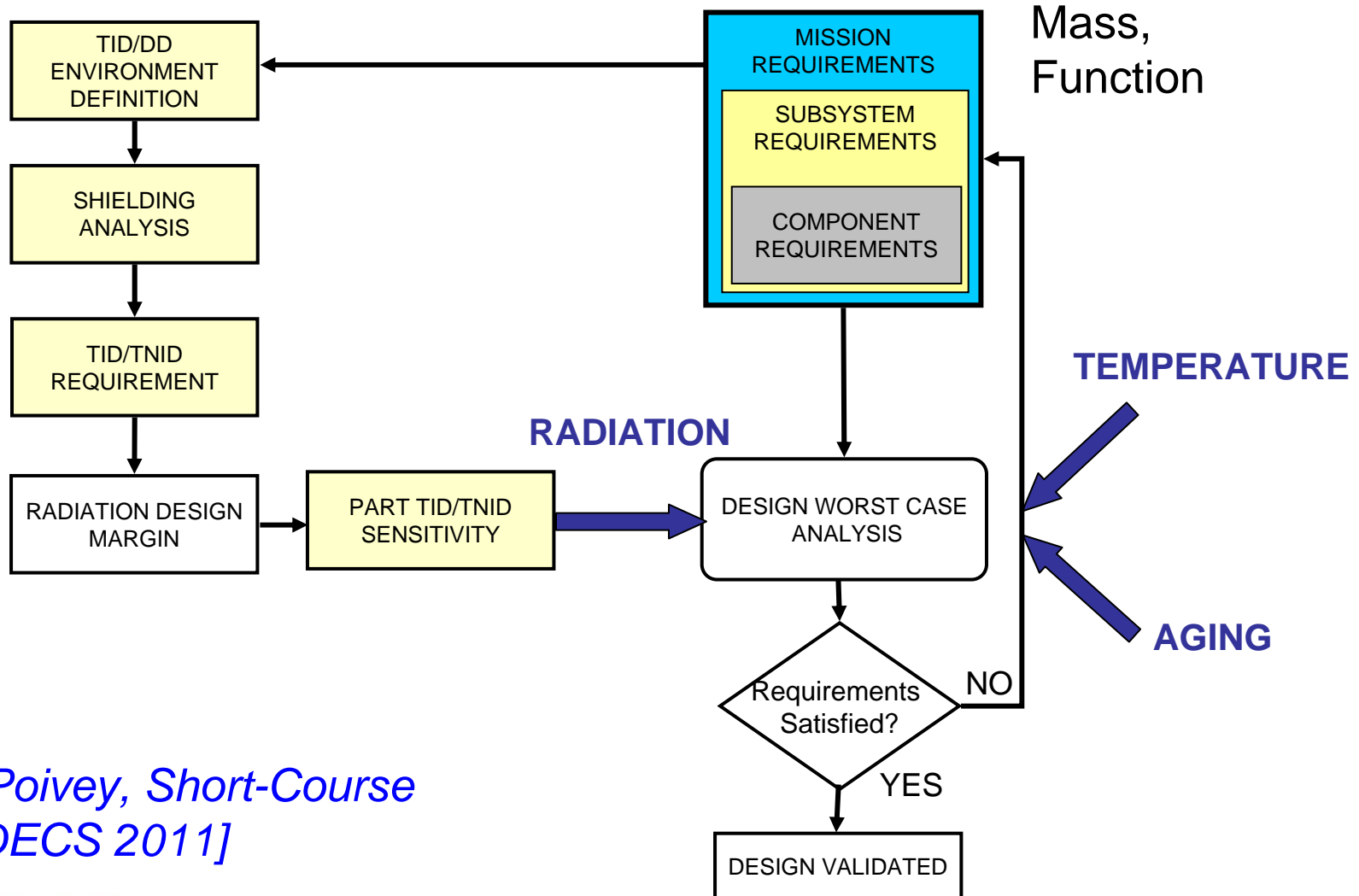
- European standard for RHA
  - *ECSS-Q-ST-60-15C* draft
  - 2 years discussions with space agencies and industrials
- Test standards:
  - *ESCC 22900*
  - *US MIL-STD1019.7*
- Test Guidelines:
  - *ASTM F1892*

# RHA Overview



*[C. Poivey, Short-Course RADECS 2011]*

# TID / TNID - Analysis Flow



[C. Poivey, Short-Course  
RADECS 2011]

# TID RHA, Scope

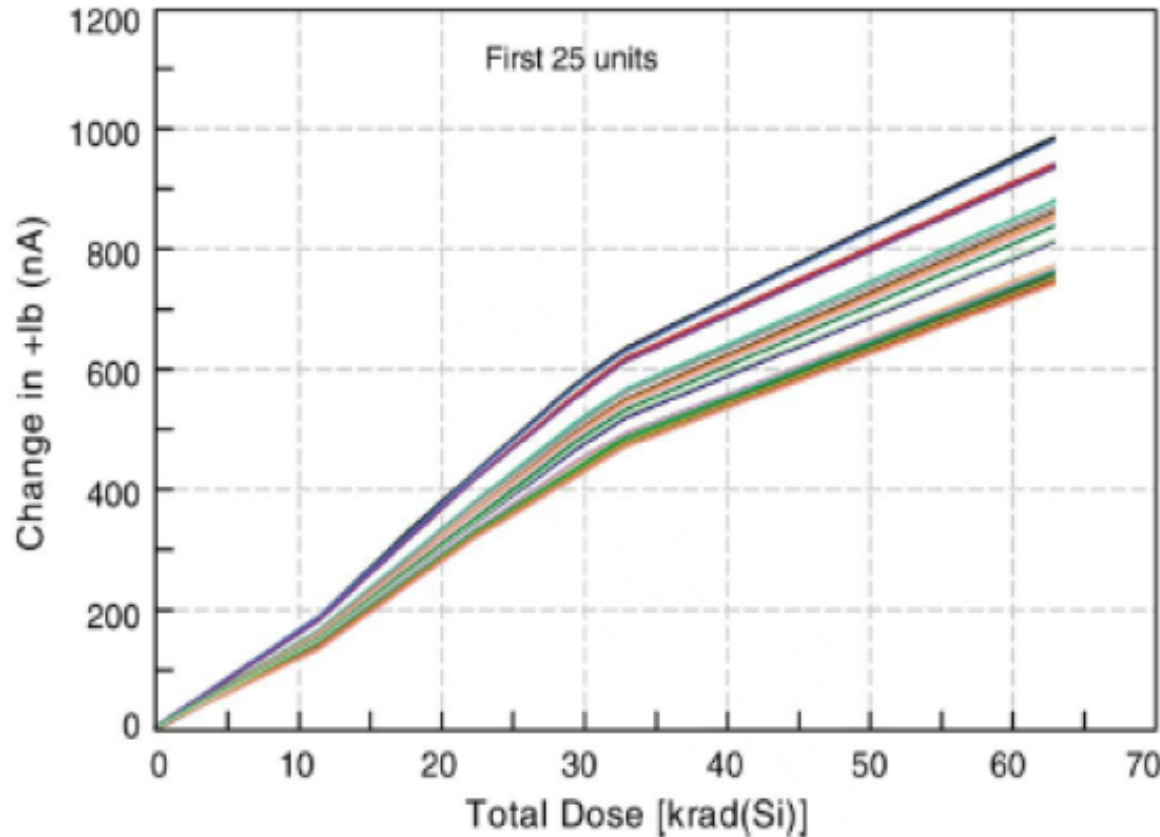
EEE part family	Sub family	TIDL
Diodes	Voltage reference	all
	Switching, rectifier, schottky	> 300 Krad-Si
Diodes microwave		> 300 Krad-Si
Integrated Circuits		all
Integrated Circuits microwave		> 300 Krad-Si
Oscillators (hybrids)		all
Charge Coupled devices (CCD)		all
Opto discrete devices, Photodiodes, LED, Phototransistors, Opto couplers		all
Transistors		all
Transistors microwave		> 300 Krad-Si
Hybrids		all

# TNID RHA Scope

Family	Sub-Family	TNIDL
CCD, CMOS APS, opto discrete devices	all	all
Integrated circuits	Silicon monolithic bipolar or BiCMOS	$> 2 \times 10^{11}$ p/cm <sup>2</sup> 50 MeV equivalent proton fluence
Diodes	Zener Low leakage Voltage reference	$> 2 \times 10^{11}$ p/cm <sup>2</sup> 50 MeV equivalent proton fluence
Transistor	Low power NPN Low power PNP High power NPN High power PNP	$> 2 \times 10^{11}$ p/cm <sup>2</sup> 50 MeV equivalent proton fluence

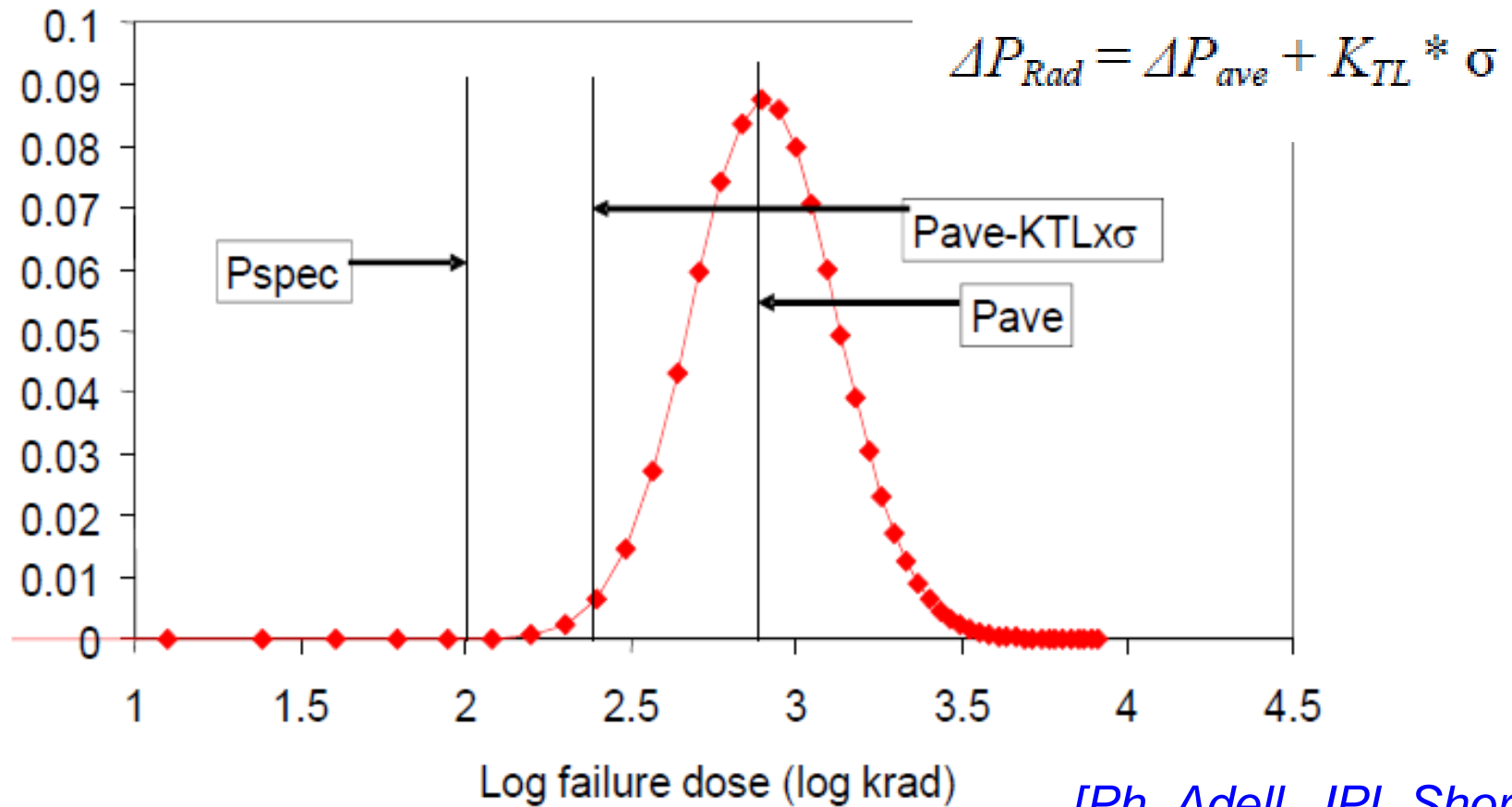


# Example of part-to-part variation in the same lot – 25 DUTs OP484



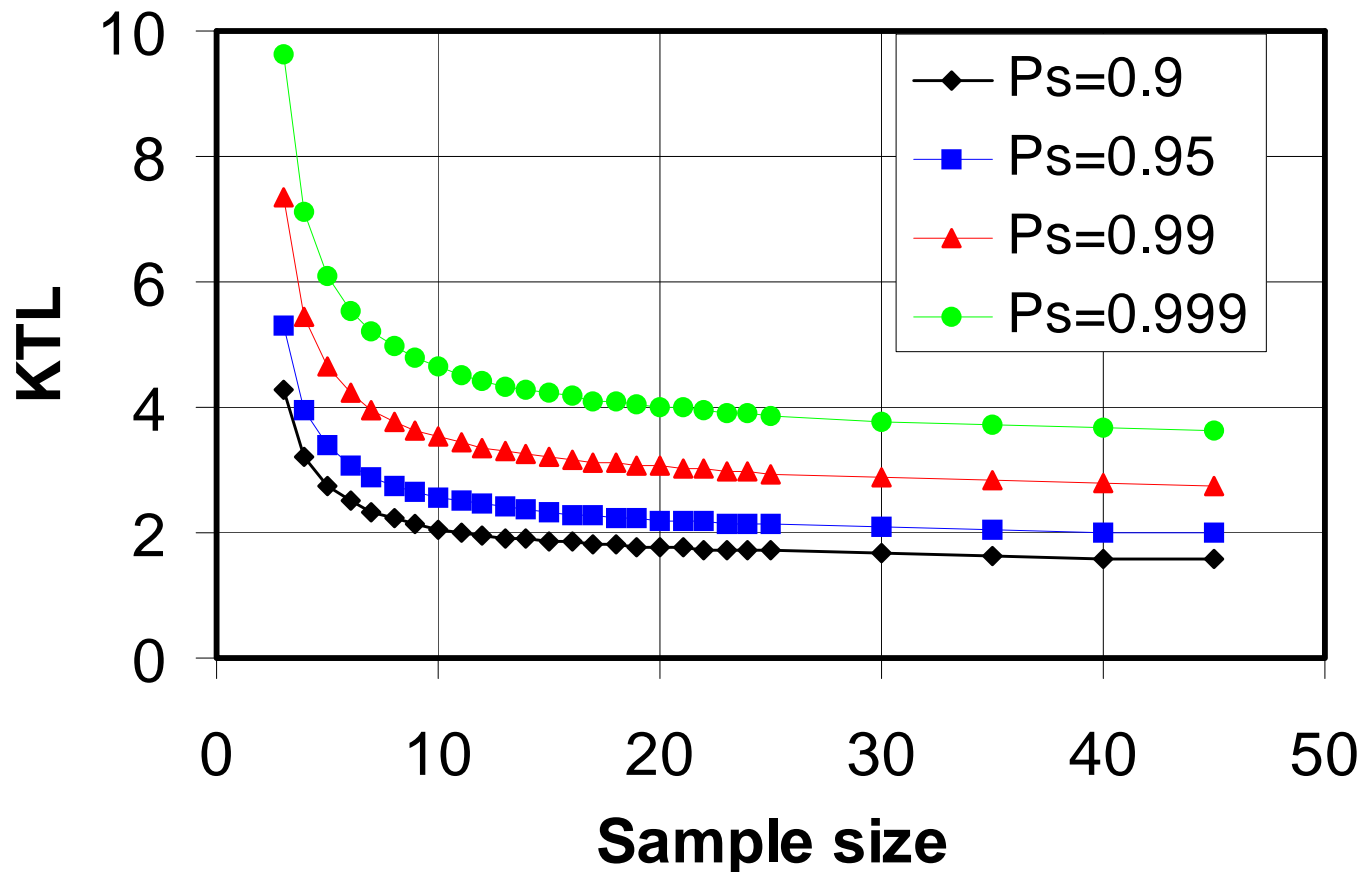
*[Ph. Adell, JPL  
Short-Course  
RADECS 2011]*

# Assumption: The degradation of electrical parameters induced by radiation follows a Log-normal distribution



[Ph. Adell, JPL Short-Course RADECS 2011]

# One-Sided Tolerance Limits, $K_{TL}$ , for 90% Confidence



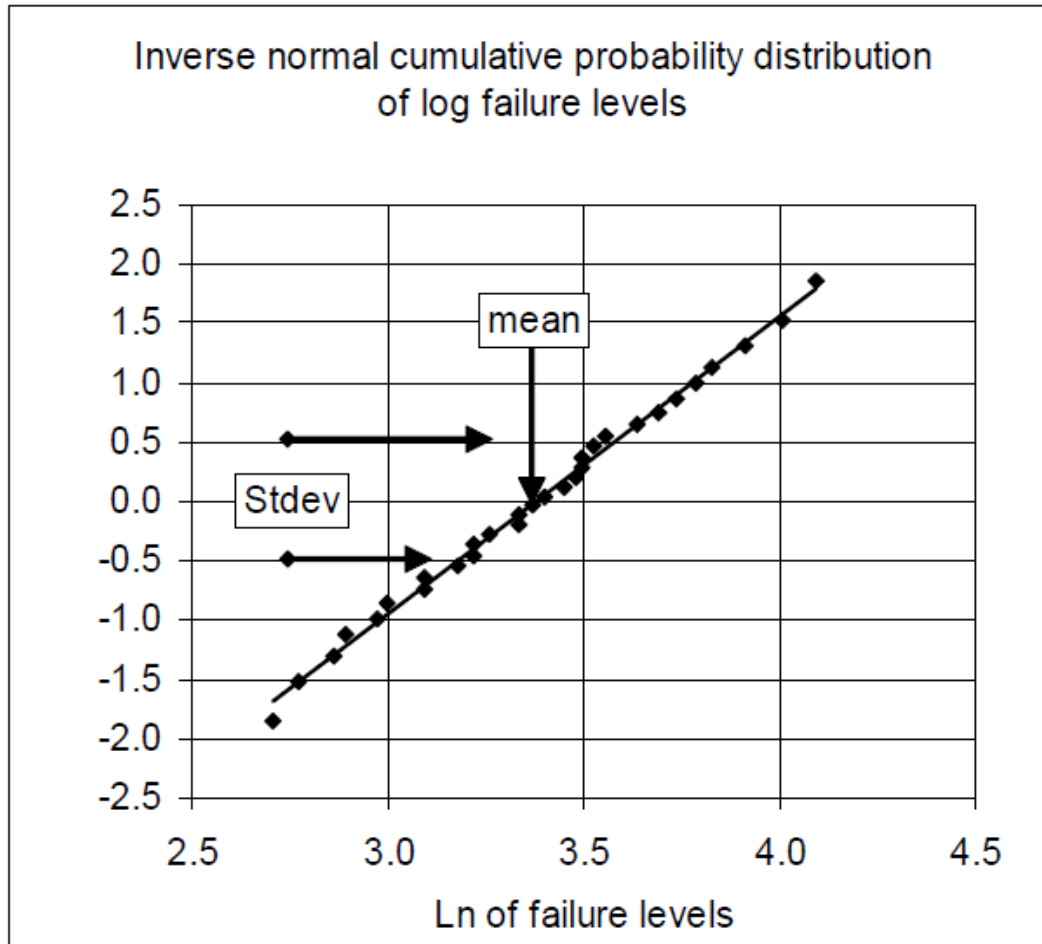
Confidence Limit (CL) and Probability of survival ( $P_s$ ) are defined by the mission

*After R Pease, Rad Phys Chem 43, 1994*



JUICE Instrument Workshop, 9-11 Nov. 2011, Darmstadt

# Statistical analysis of TID results: extraction of the normal distribution parameters: mean – standard deviation

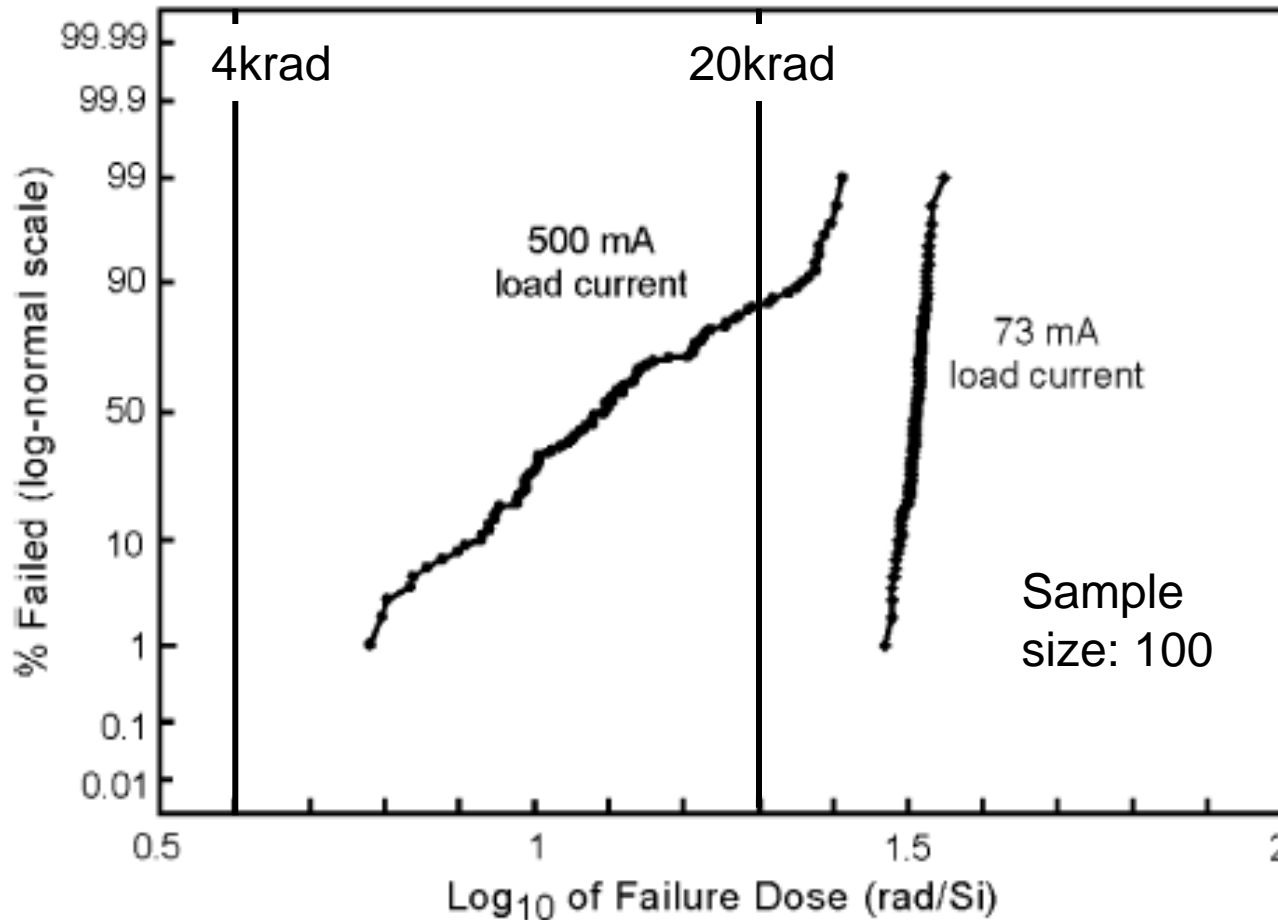


Statistical analysis: determination of worst-case parameter deltas for Worst-Case-Analysis

*[R. L. Pease,  
Short-Course  
NSREC 2004]*

# Example of statistical TID analysis: LM117 voltage regulator

## Large distributions of output voltage failure doses



- The operating conditions have a strong impact on the radiation response
- System designers will have to work closely with radiation effects engineers

*[Johnston and Rax,  
TNS Aug. 2010]*

# Radiation Design Margin

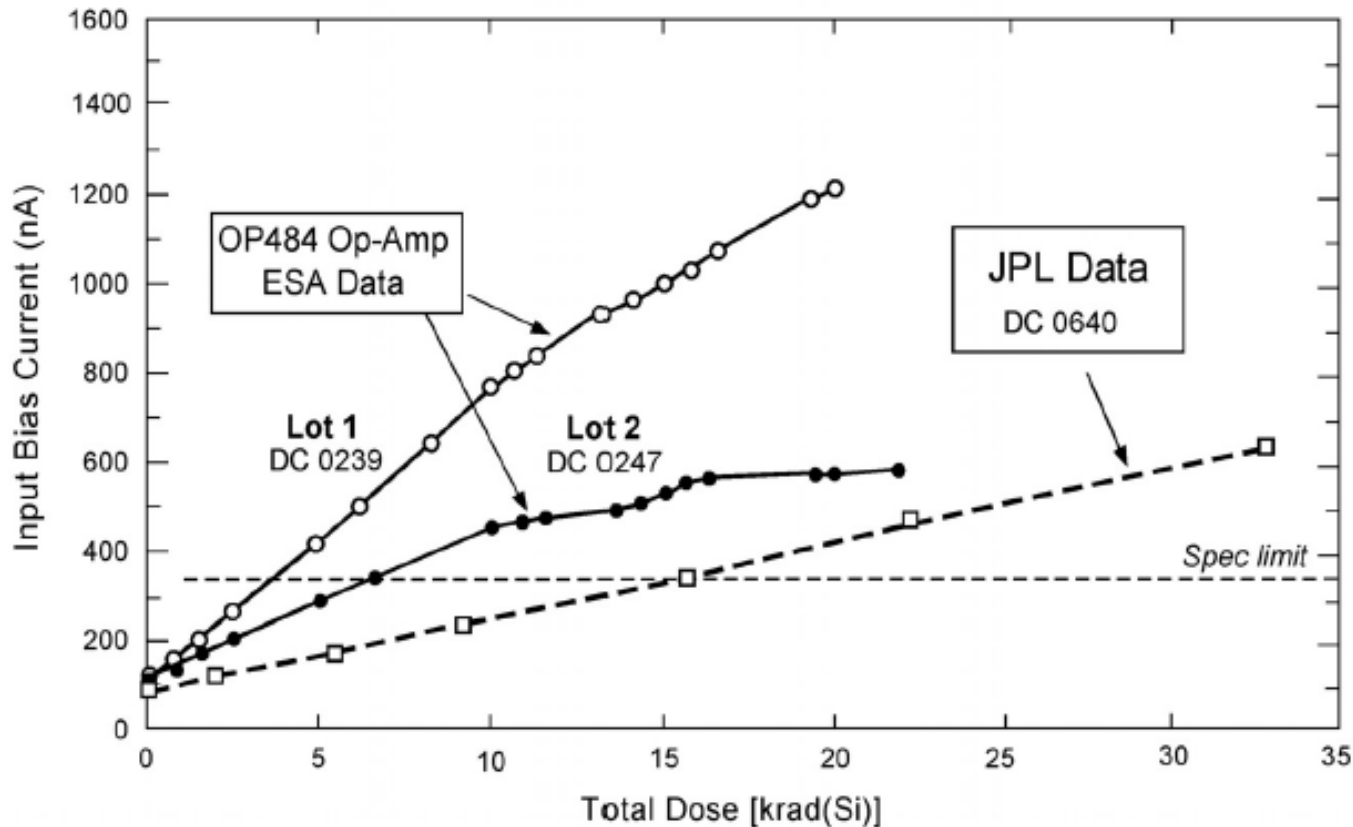
- RDM is the ratio of device radiation tolerance TIDS out of device radiation requirement TIDL
  - Uncertainties, variability in radiation environment
  - Part to part variations
  - Lot to Lot variations
- Applies also to TNID

*[C. Poivey, Short-Course  
RADECS 2011]*

# Example of Lot-to-lot variability

## The test of the flight lot is mandatory for accurate statistical analysis

Figure 43. Linear regulator  $I_{out}$  degradation as a function of total dose @ 50 mrad/s.



- Average input bias current degradation for 3 Date Codes (lots)
- TID/TNID irradiation tests to be performed on same lot as FM lot

[Ph. Adell, JPL Short-Course RADECS 2011]

# Typical RDMs and RADLAT policy used in programs

- ESA internal RHA
  - $DM > 2$  on the WC failure level + systematic lot testing policy
  - Part categorization criteria defined to guarantee a Ps of 90% with a CL of 90% + systematic lot testing policy
- The RDM of 2 can be reduced to 1 if
  - Statistical radiation analysis performed on large sample size
  - Test of the Flight lot
  - In the flight operating conditions or worst-case
- ESA internal RHA are tailored to project requirements

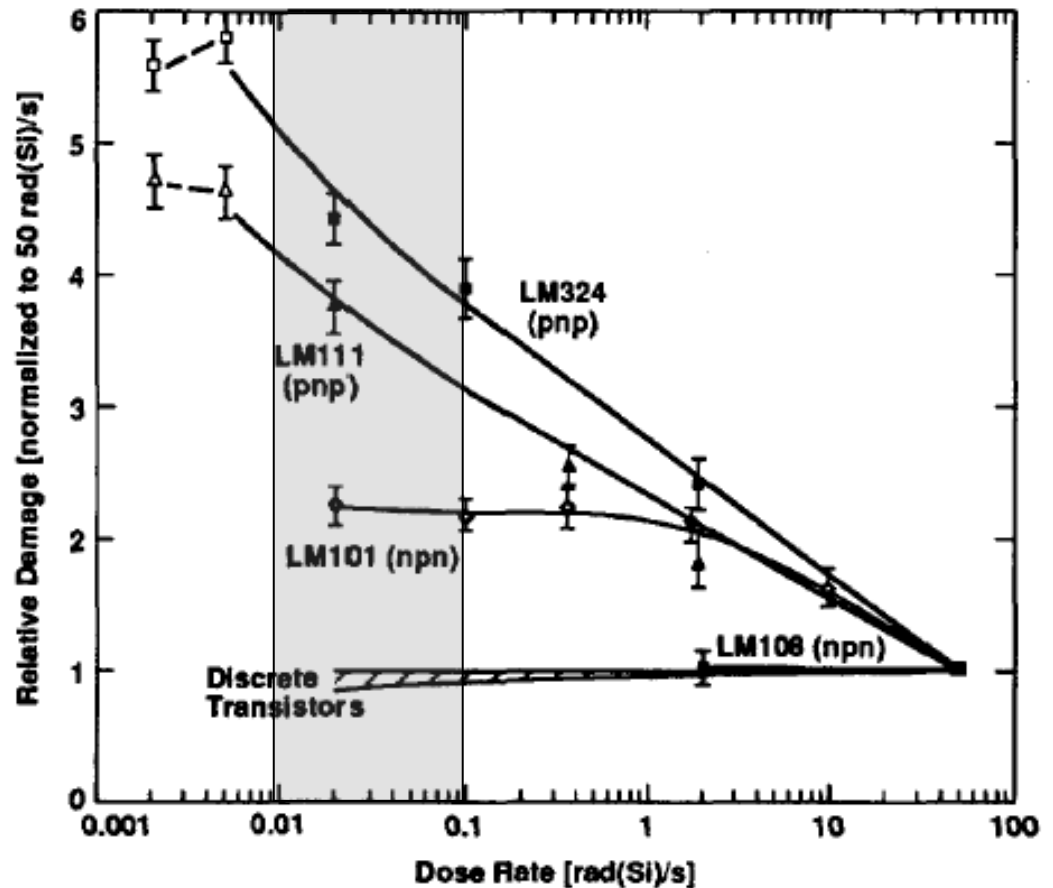


# ELDRS in Linear - bipolar based – components: Enhanced Low Dose Rate Sensitivity

Laplace mission receives most of its TID in the vicinity of Jupiter's moons.

For example, 200krad received within ~40 days results in an average dose rate of ~**200rad/h**

The low dose rate window in ESCC22900: **36-360 rad/h (10-100mrad/s)** is well adapted to the Laplace environment



[A. H. Johnston, et al. TNS Dec. 1994]

# Technology Demonstration Activities

## Components for Power Systems

# Components for Power Systems

- MOS, CMOS
  - CMOS Logic
  - Power MOSFET (60,10, 200V; N channel, P channel)
- Bipolar – BiCMOS
  - Voltage reference (bandgap and Zener)
  - Operational amplifier
  - Voltage Comparator
  - PWM (Pulse Width Modulator) controller
  - Analog Multiplexer
  - MOSFET driver
  - Bipolar transistor (NPN, PNP, small signal, medium power)
  - Schottky diode (small signal, power)
- Optoelectronics
  - Optocoupler



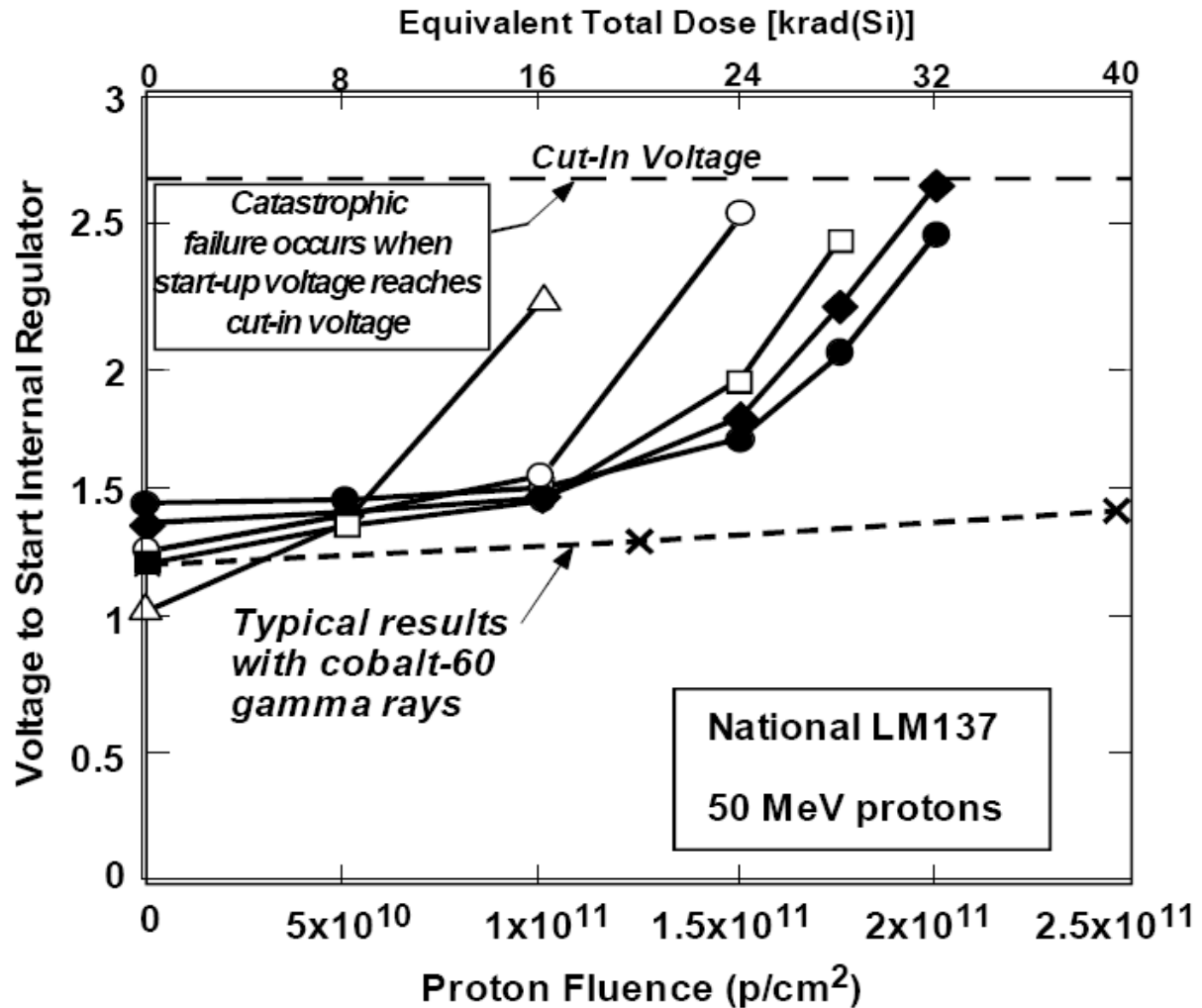
**ELDRS  
and  
DD**



# Displacement Damage in bipolar technologies

Voltage Regulator  
5 DUTs:  
large variability

[B. G. Rax et al.  
TNS Dec. 1999]



# Objectives of the Study

- Survey the components required to meet Laplace power requirements
- If radiation data is not available on selected components, they shall be characterized to the **combined effects** of TID up 400krad - and TNID up to a 60 MeV protons fluence of  $2 \cdot 10^{11}$  #/cm<sup>2</sup>
- The results of the study are used as inputs to a subsequent activity to design power systems for the Laplace mission. Can we design power systems employing component that may degrade significantly when exposed to Laplace radiation levels?

# Final List of Tested Parts

DESCRIPTION	PART-TYPE	MFR	FOR TESTING	TECHNOLOGY	TID	ELDRS	PROTONS
NPN POWER SILICON SWITCHING TRANSISTOR	2N5154	MSC	JANSF2N5154	BIPOLAR	N	Y	Y
NPN SILICON SWITCHING TRANSISTOR	SOC2222A	STM	SOC2222AK2	BIPOLAR	N	Y	Y
DUAL-TRANSISTOR, NPN, SILICON	2N2920A	STM	SOC2N2920AK2	BIPOLAR	N	Y	Y
PNP SILICON AMPLIFIER TRANSISTOR	2N3637	MSC	JANSR2N3637	BIPOLAR	N	Y	Y
PNP SMALL SIGNAL SILICON TRANSISTOR	SOC2907A	STM	SOC2907AK2	BIPOLAR	N	Y	Y
DUAL-TRANSISTOR, PNP, SILICON	2N3810	STM	SOC2N3810AK2	BIPOLAR	N	Y	Y
LOW POWER, NPN (< 2WATTS)	2N3700	STM	SO3700SW	BIPOLAR	N	Y	Y
RAD HARD HIGH FREQUENCY HALF BRIDGE DRIVER	HS-2100RH	INTERSIL	IS9-2100ARH/PROTO	DI RSG	N	Y	Y
DUAL, NON INVERTING POWER MOSFET DRIVERS	HS-4424BRH	INTERSIL	HS9-4424BRH/PROTO	DI RSG BICMOS	N	Y	Y
LOW POWER QUAD BIPOLAR OPERATIONAL AMPLIFIER	LM124AW	NATIONAL	5962R9950402V**	BIPOLAR	N	Y	Y
LOW POWER QUAD BIPOLAR OPERATIONAL AMPLIFIER	RHF43	STM	RHF43K2	BIPOLAR	N	Y	Y
RAD TOLERANT VERSION OF 4N49	OLS449	ISOLINK	OLS449	-	N	Y	Y
LINEAR OPTOCOUPLER	OLH7000	ISOLINK	OLH7000-0011	-	Y <sup>(1)</sup>	N	Y
SEE HARD HIGH SPEED, CURRENT MODE PWM	IS-1845ASRH	INTERSIL	IS7-1845ASRH/PROTO	DI RSG	N	Y	Y
SEE HARD HIGH SPEED, DUAL OUTPUT PWM	IS-1825ASRH	INTERSIL	IS1-1825ASRH/PROTO	DI RSG	N	Y	Y
SEE HARD QUAD VOLTAGE COMPARATOR	IS-139ASRH	INTERSIL	IS9-139ASRH/PROTO	DI RSG	N	Y	Y
RAD HARD 2.5V REFERENCE	IS-1009RH	INTERSIL	IS2-1009RH/PROTO	DI EBHF	N	Y	Y

# Technology Demonstration Activities

## Optocouplers, sensors and detectors

- 10 different types of « slow » and « fast » optocouplers from Micropac, Isolink, Avago.
- TID/TNID tests:
  - Dose (Co60), 36-360 rad/h until 200krad.
  - DD proton, 3 energies (30, 60 et 200MeV).
  - DD neutron 1MeV; separate contributions from TID and TNID
- SEE tests:
  - Three « fast » optocouplers
    - Isolink OLH7000
    - Micropac 66193 et
    - Avago HCPL5431)
  - 3 different proton energies (100, 175 et 250MeV).
- Combined effects: SEE tests of previously TID/TNID irradiated optocouplers
- Are these technologies capable of surviving the Laplace radiation environment?

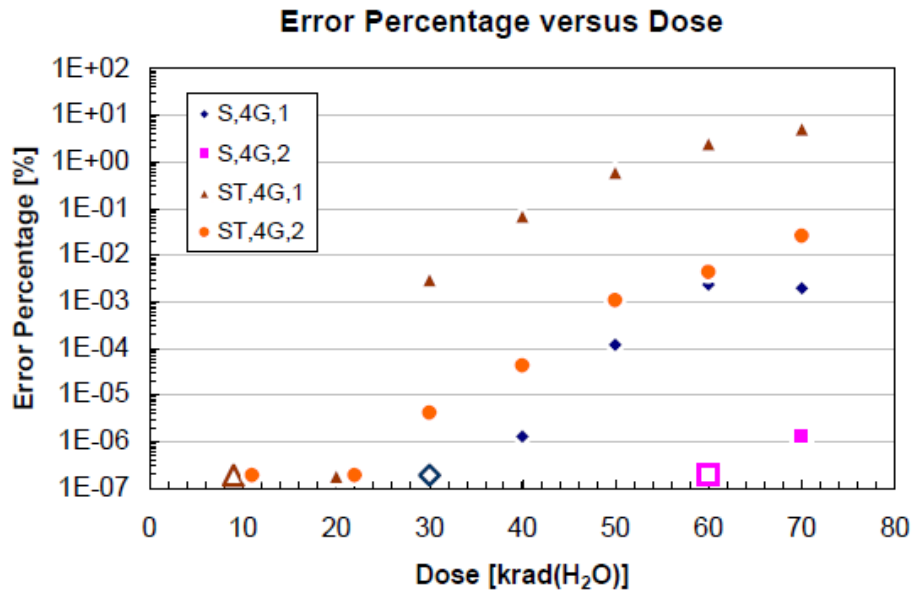


# Technology Demonstration Activities

Radiation testing of  
candidate memories  
for Laplace mission

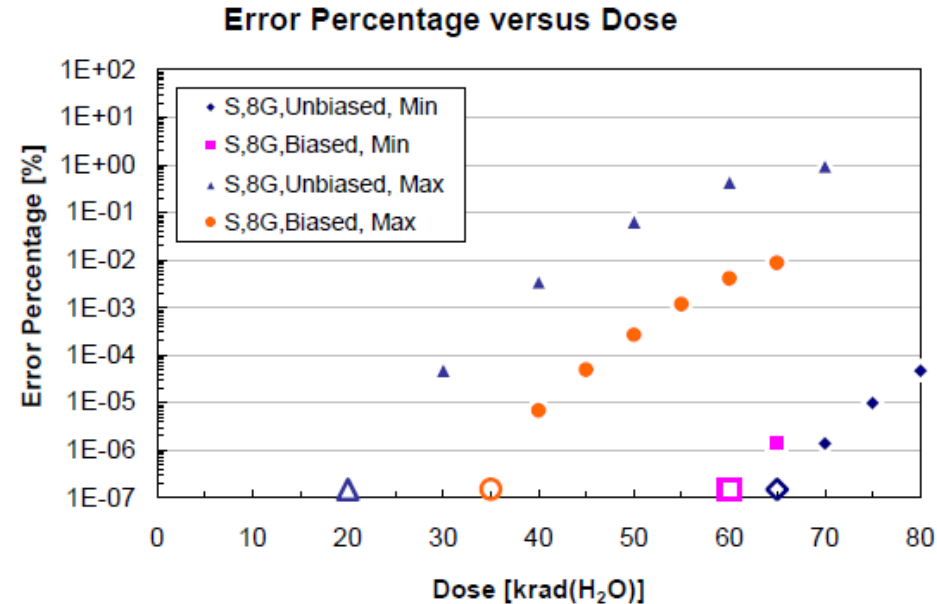
# 50nm technologies 8-Gbits NAND-Flash TID tolerance ~ 20 krad

8-Gbits NAND-Flash, Samsung & ST



Significant variation, even for same “date code” parts

8-Gbits NAND-Flash, Samsung

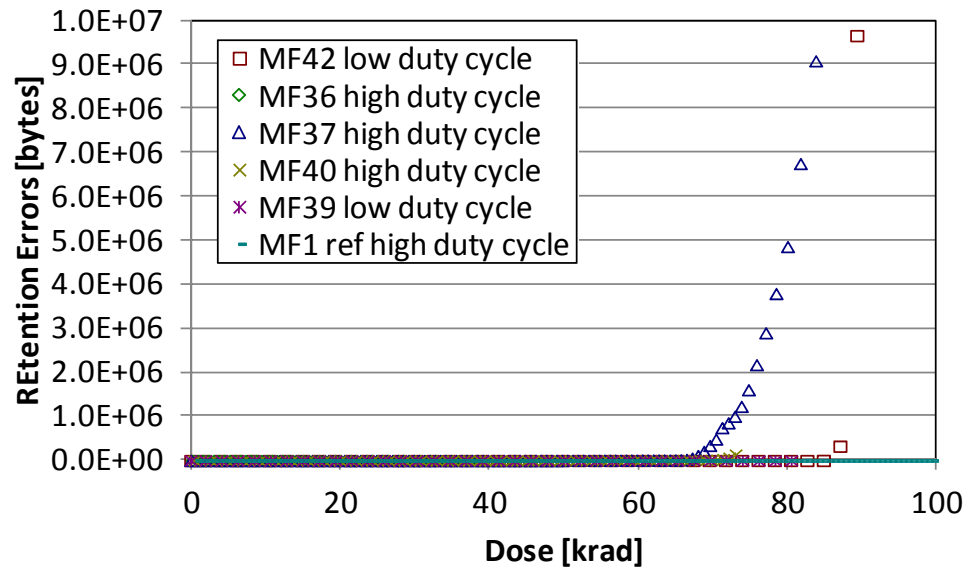


Biased vs unbiased tests:  
10 + 8 samples

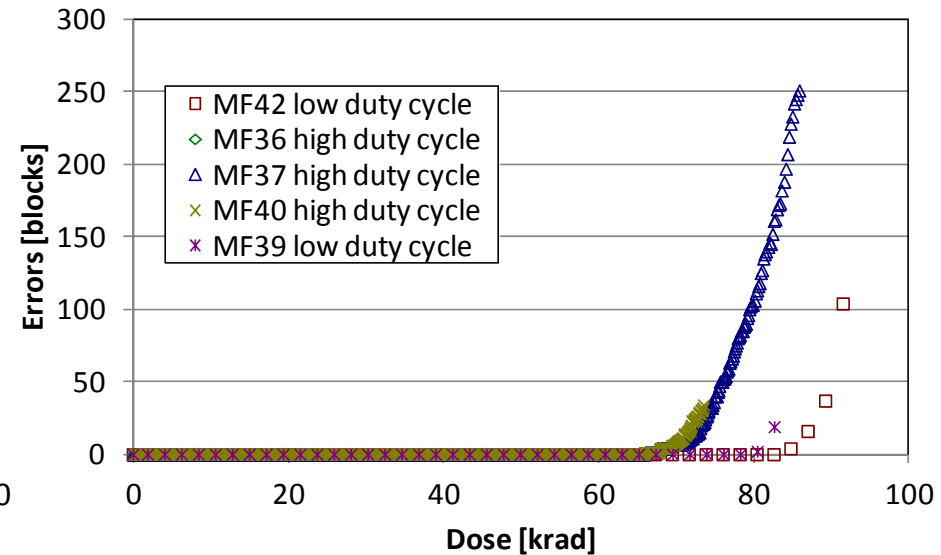
*[Schmidt, IDA, 2008] under ESA contract*

# New generation, 34-nm technology, 16-Gbit Single-Level-Cell Flash Memories : Micron MT29F16G08ABABA Preliminary TID tolerance ~65krad

SLC: Retention Errors



SLC: Block Erase Fails



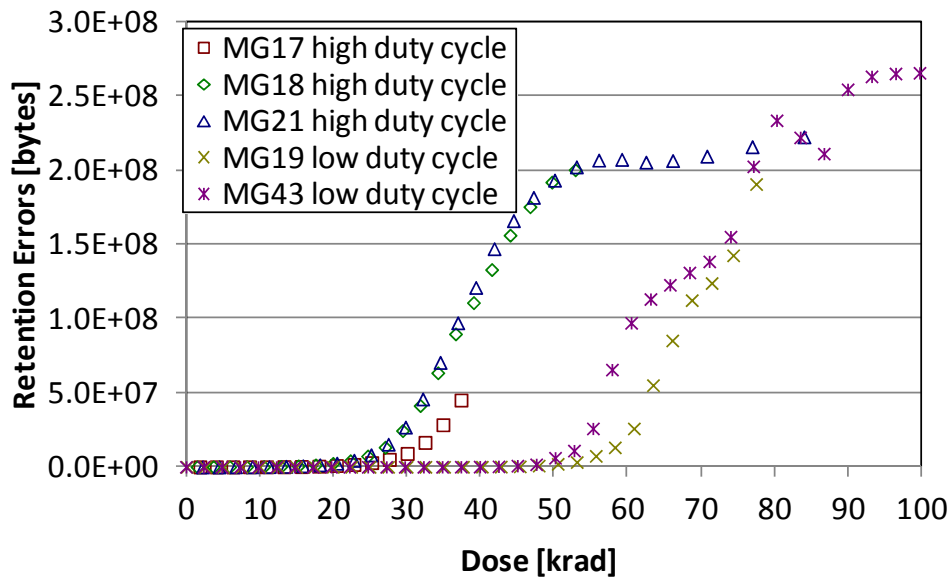
ESA Contract 2011-2012 RFQ3-13074/10/NL/PA

M. Bagatin, S. Gerardin, A. Paccagnella, Università di Padova

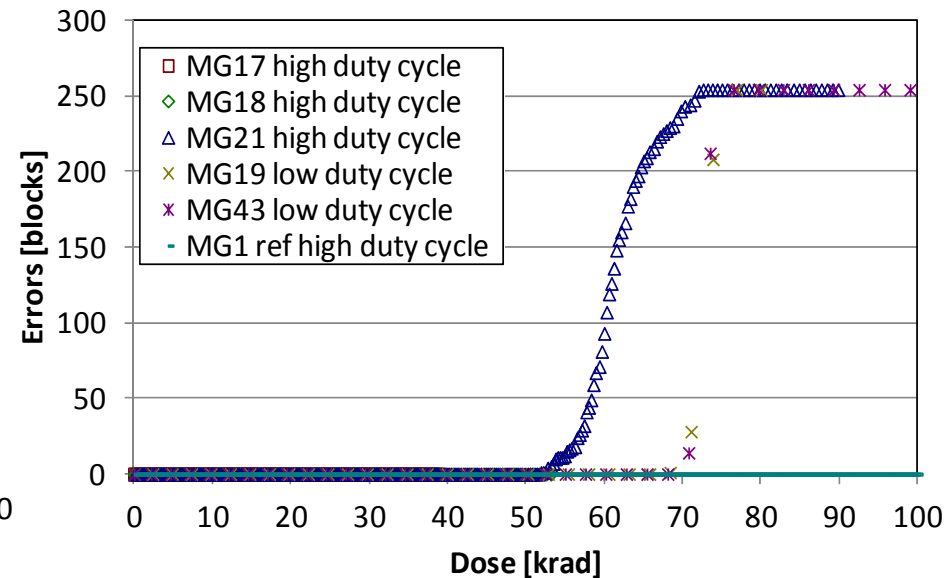


# But Multi-Level-Cell (two-bit-per-cell) Flash Memories 25-nm technology, 32-Gbit: Micron MT29F32G08CBACA do not behave as well: TID tolerance ~ 20 krad

**MLC: Retention Errors**



**MLC: Block Erase Fails**



ESA Contract 2011-2012 RFQ3-13074/10/NL/PA

M. Bagatin, S. Gerardin, A. Paccagnella, Università di Padova

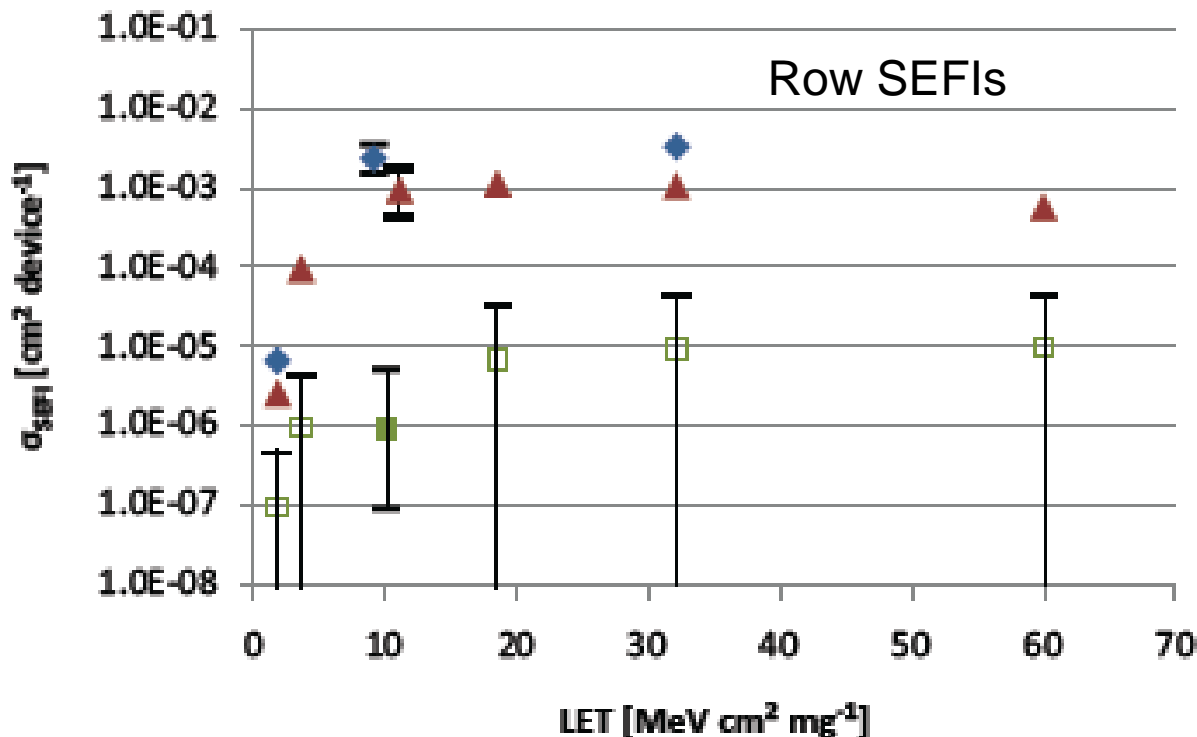


# Some SEE results on DDR3 memories: SEFIs are the dominant source of errors

Micron MT41J256M8 (2 samples, date code 0949)

Samsung K4B2G0846D (3 samples, date code 1006)

Nanya NT5CB256M8BN (3 samples, date code 1026)



[IDA, Radecs2011,  
under Laplace  
contract]

Samsung  
behaves  
significantly better

# Conclusion

- Radiation environment is severe, but nothing impossible
- Will require careful part selection and RHA process at all levels (systems – components)
  - Radiation tests of electronic components
    - Statistical radiation analysis, to reduce the RDM
    - Tests of the Flight lots
    - in the application conditions (or worst)
  - System Worst-case analysis
    - Robust designs
  - RHA process to be started in early project phases
- Compromises between shielding mass & radiation tolerance

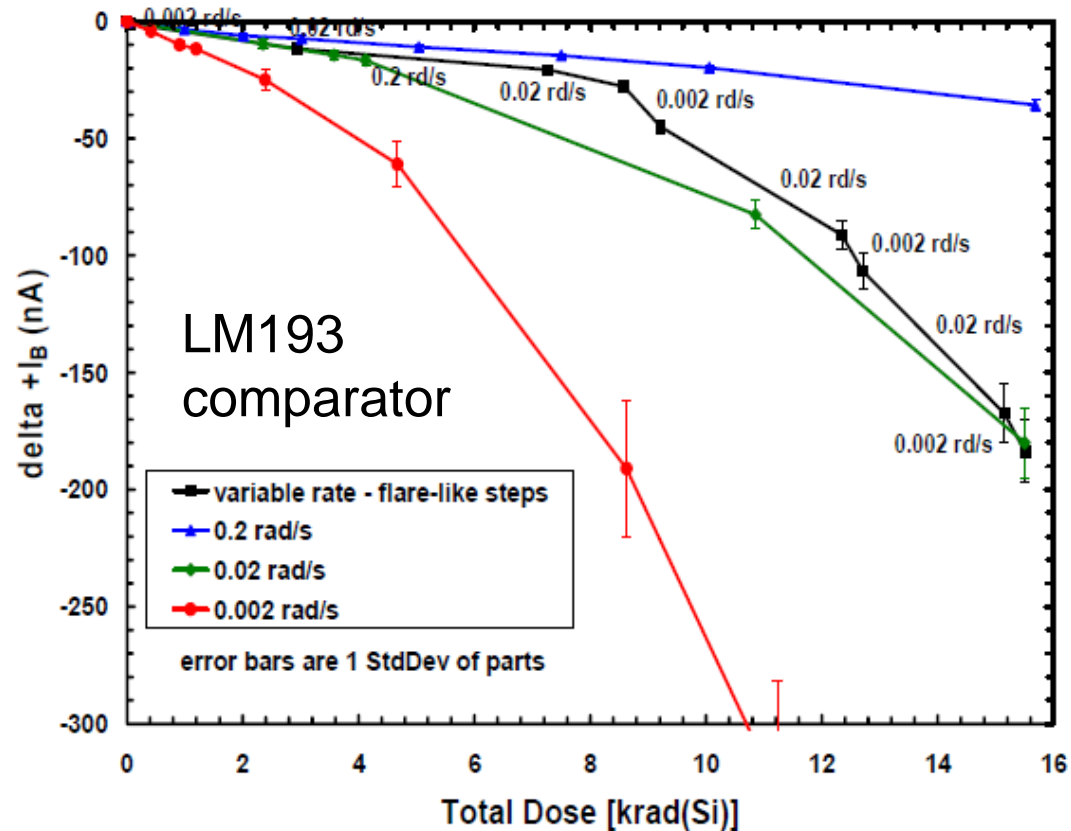
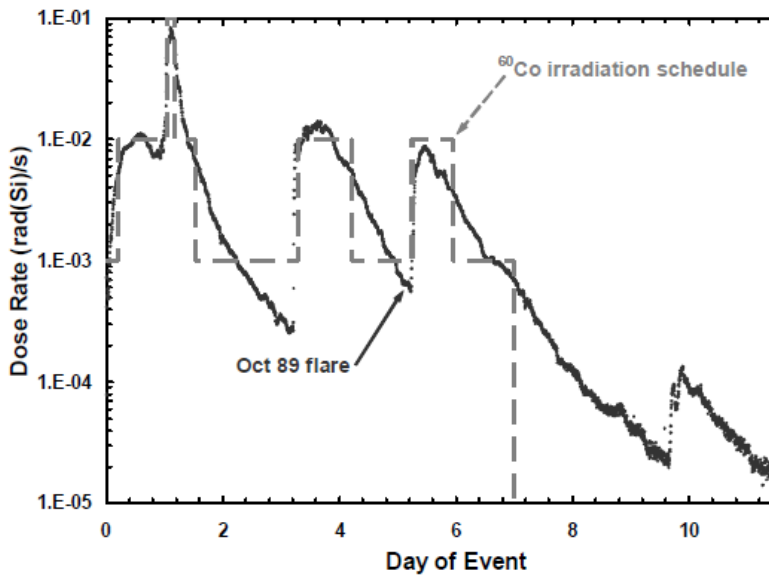
# Links to

- ESCC web site
  - <https://spacecomponents.org/>
  - EPPL
- ESCIES web site
  - <https://escies.org/>
  - Test facilities
  - Standards and handbooks
  - Radiation database

# Back-up slides



# Example of the Oct. 89 solar flare: applicable to variable dose rate missions



low dose rate window in the  
ESCC22900:  
**36-360 rad/h = 10-100mrad/s**

[R. D. Harris, TNS Dec. 2008]